# 502724431 03/17/2014

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
FU-AN LI	02/14/2014
CHENG-CHUN TSAI	02/14/2014
TING-HSIEN CHEN	02/14/2014
MU-KAI TUNG	02/14/2014
BEN-ZU WANG	02/14/2014
PO-JEN SHIH	02/14/2014
HUNG-HSIN LIANG	02/14/2014

## **RECEIVING PARTY DATA**

Name: TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.		
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Internal Address: SCIENCE-BASED INDUSTRIAL PARK		
City: HSINCHU		
State/Country:	TAIWAN	
Postal Code:	3000	

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number	
Application Number:	14174303	

#### **CORRESPONDENCE DATA**

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DATE SIGNED:	03/17/2014
	FAILNI

REEL: 032452 FRAME: 0192

## Total Attachments: 2 source=00424040#page1.tif source=00424040#page2.tif

PATENT REEL: 032452 FRAME: 0193

#### ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title)\_\_\_\_\_\_ SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THEREOF

The PATENT RIGHTS referred to in this agreement are:

(*check one*) a patent application for this invention, executed by the ASSIGNOR(S) concurrently with this assignment.

U.S. patent application Serial No. <u>14/174,303</u>, filed <u>February 6, 2014</u>

a U.S. patent application based on PCT International Application

No.\_\_\_\_\_\_filed on (date)\_\_\_\_\_(U.S. patent application Serial No.\_\_\_\_\_\_, if known).

U.S. patent No.\_\_\_\_, issued\_\_\_\_\_.

The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

(*check one*)  $\boxtimes$  U.S. patent rights only.

Worldwide patent rights. In this case, the assignee shall have the right to claim the benefit of the filing date of any U.S. or foreign patent application for this invention.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures appear on page 2 of this Assignment and any Supplemental Sheet(s).

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.

(Address) NO.8, LI-HSIN RD.6, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU,

TAIWAN 300, R.O.C.

The ASSIGNEE is:

(check one) An individual.

A Partnership.

A Corporation of <u>TAIWAN, R.O.C.</u> (specify state or country)

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and valuable consideration, receipt of which is acknowledged, hereby assign(s) the following

rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable

provisions, based on any earlier patent applications for this invention.

### PATENT REEL: 032452 FRAME: 0194

# THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO ASSIGNEE: TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. INVENTION TITLE: SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THEREOF

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

Fu-An LI	Fu-An Li	2014,2,14
Name of sole or first inventor	Signature	Date
Cheng-Chun TSAI Name of second inventor, if any	Signature	2014 2-14. Date
Ting-Hsien CHEN	Ting-Usien CHEN	Zott. 2.14
Name of third inventor, if any	Signature	Date
Mu-Kai TUNG	Mu-Kai Tunf	2014, 2.14
Name of fourth inventor, if any	Signature	Date
Ben-Zu WANG Name of fifth inventor, if any	<u>Ben-Zu</u> WAWG Signature	 Date
Ivanie of man inventor, if any	orgnature	Date
Po-Jen SHIH	PB-Jen 5434	2014. 2.14

Name of sixth inventor, if any

Hung-Hsin LIANG Name of seventh inventor, if any

Signature

Date

2014. 2.14.

Date

PATENT **REEL: 032452 FRAME: 0195** 

**RECORDED: 03/17/2014** 

Signature